

P-Channel Logic Level Enhancement Mode MOSFET with Schottky Diode

MSFA0M02X8

MOSFET product Summary

BV_{DSS}	-20V
$R_{DSON(MAX)}$	100m Ω
I_D	-3A

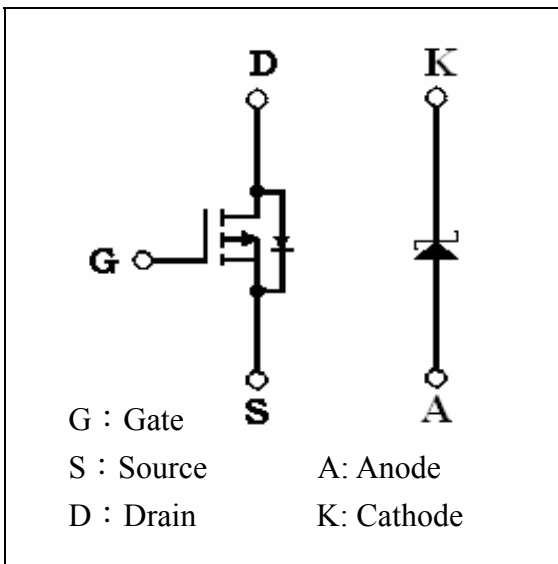
Schottky Product Summary

V_{KA}	20V
V_F	0.46V
I_F	1A

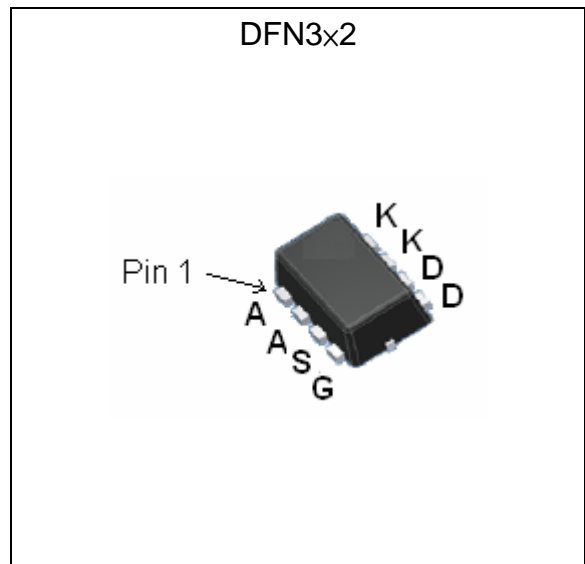
Features

- Simple drive requirement
- Low on-resistance
- Fast switching speed
- Pb-free lead plating and halogen-free package

Symbol



Outline





Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Limits	Unit	
Drain-Source Breakdown Voltage	BV_{DSS}	-20	V	
Gate-Source Voltage	V_{GS}	± 12	V	
Continuous Drain Current @ $T_A=25^{\circ}\text{C}$	I_D	-3	A	
Continuous Drain Current @ $T_A=70^{\circ}\text{C}$	I_D	-2.4		
Pulsed Drain Current (Note 1)	I_{DM}	-12		
Average Forward Current (Schottky)	I_F	1		
Pulsed Forward Current (Schottky)	I_{FM}	3		
Power Dissipation (MOSFET)	$T_A=25^{\circ}\text{C}$	P _D	1.5	W
	$T_A=70^{\circ}\text{C}$		0.9	
Power Dissipation (Schottky)	$T_A=25^{\circ}\text{C}$		1.2	
	$T_A=70^{\circ}\text{C}$		0.76	
Operating Junction and Storage Temperature Range	$T_j; T_{stg}$	-55~+150	$^{\circ}\text{C}$	

Note : 1. Pulse width limited by maximum junction temperature. Duty cycle $\leq 1\%$.

Thermal Resistance Ratings

Parameter	Symbol	Maximum	Unit
Thermal Resistance, Junction-to-case(MOSFET)	$R_{th,j-c}$	40	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-ambient(MOSFET)	$R_{th,j-a}$	85	
Thermal Resistance, Junction-to-case(Schottky)	$R_{th,j-c}$	50	
Thermal Resistance, Junction-to-ambient(Schottky)	$R_{th,j-a}$	105	

Electrical Characteristics ($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-20	-	-	V	$V_{GS}=0V, I_D=-250\mu A$
$V_{GS(th)}$	-0.3	-0.75	-1.2	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 12V, V_{DS}=0V$
I_{DSS}	-	-	-1	μA	$V_{DS}=-16V, V_{GS}=0V$
	-	-	-10	μA	$V_{DS}=-16V, V_{GS}=0, T_j=125^{\circ}\text{C}$
$I_{D(ON)}$	-3	-	-	A	$V_{DS}=-5V, V_{GS}=-4.5V$
* $R_{DS(ON)}$	-	85	100	m Ω	$I_D=-3A, V_{GS}=-4.5V$
	-	120	150		$I_D=-2.5A, V_{GS}=-2.5V$
* G_{FS}	-	4.5	-	S	$V_{DS}=-5V, I_D=-3A$
Dynamic					
C_{iss}	-	1033	-	pF	$V_{DS}=-10V, V_{GS}=0, f=1\text{MHz}$
C_{oss}	-	386	-		
C_{rss}	-	367	-		
R_g	-	6.5	-	Ω	$V_{GS}=15\text{mV}, V_{DS}=0V, f=1\text{MHz}$

*t _{d(ON)}	-	15	-	ns	V _{DS} =-10V, I _D =-1A, V _{GS} =-4.5V, R _{GS} =6Ω
*t _r	-	30	-		
*t _{d(OFF)}	-	35	-		
*t _f	-	30	-		
*Q _g	-	10	-	nC	V _{DS} =-10V, I _D =-3A, V _{GS} =-4.5V
*Q _{gs}	-	3.6	-		
*Q _{gd}	-	3	-		
Source-Drain Diode					
*V _{SD}	-	-	1.2	V	V _{GS} =0V, I _F =I _S
*I _S	-	-	-2.5	A	
*I _{SM}	-	-	-10	A	

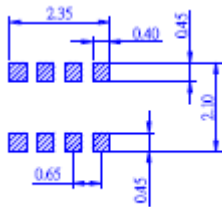
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Schottky Electrical Characteristics (T_A=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
*V _F	-	0.40	0.46	V	I _F =0.5A
	-	0.47	0.56		I _F =1A
	-	0.44	0.53		I _F =1A, T _J =125°C
I _{RM}	-	0.008	0.08	mA	V _R =5V
	-	2.8	28		V _R =5V, T _J =125°C
	-	0.009	0.09		V _R =20V
	-	3.2	32		V _R =20V, T _J =125°C
C _T	-	30	-	pF	V _R =10V

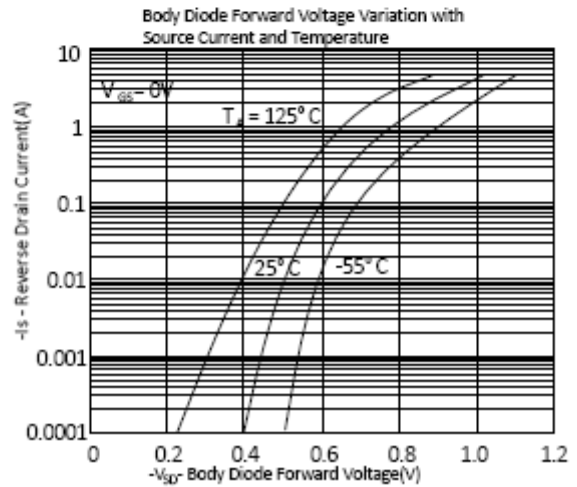
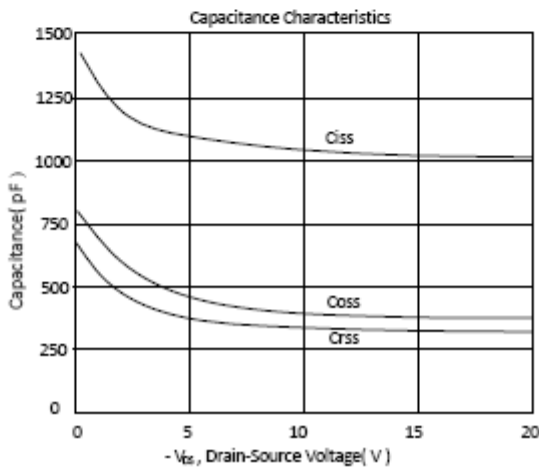
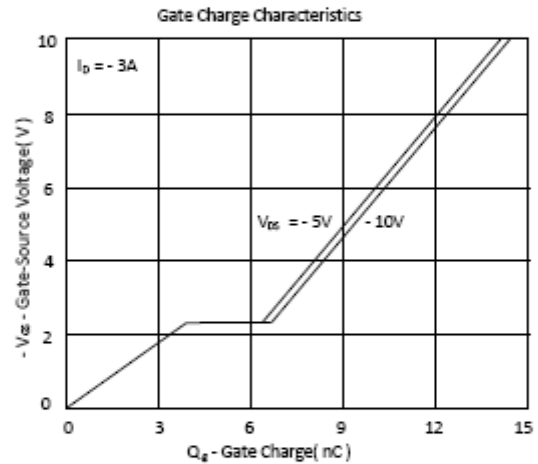
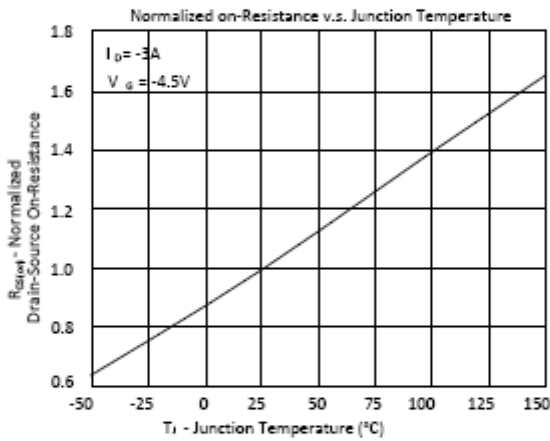
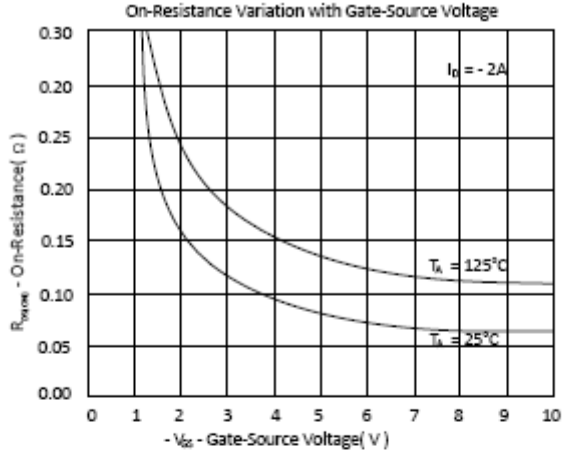
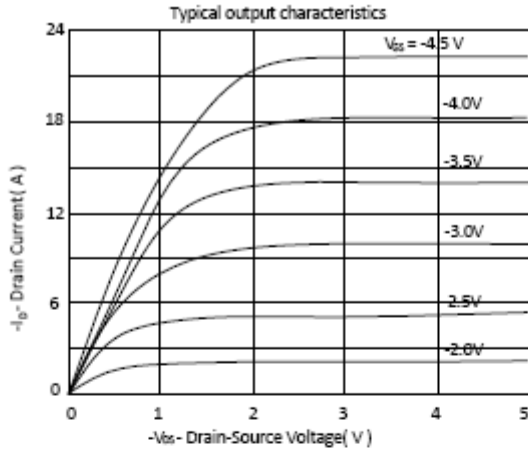
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended Footprint



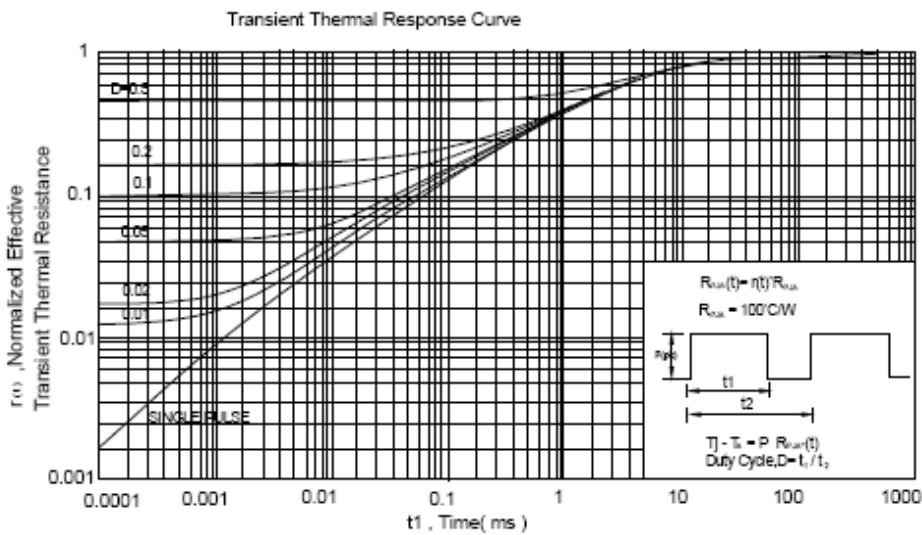
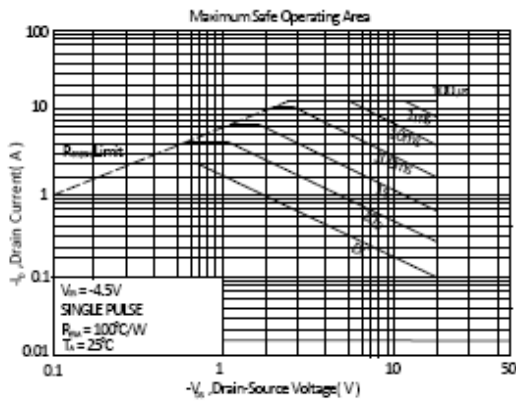
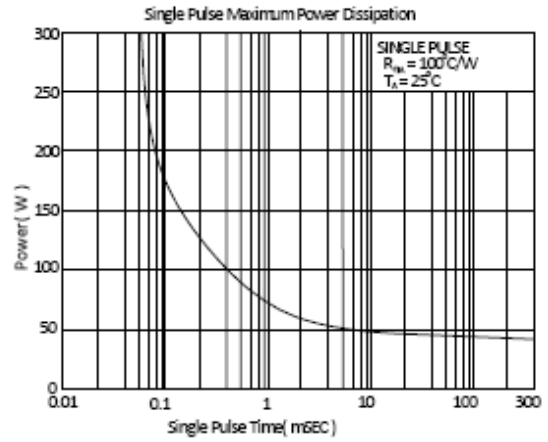
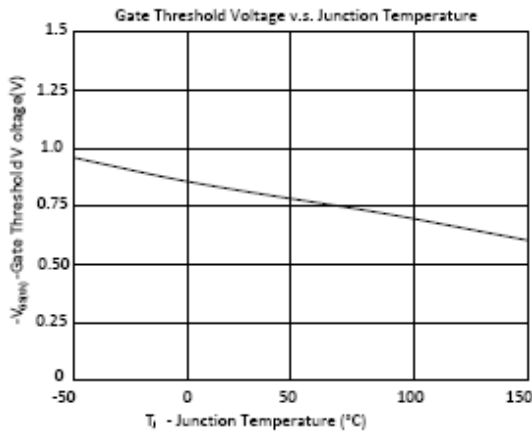
Characteristic Curves

MOSFET TYPICAL CHARACTERISTICS

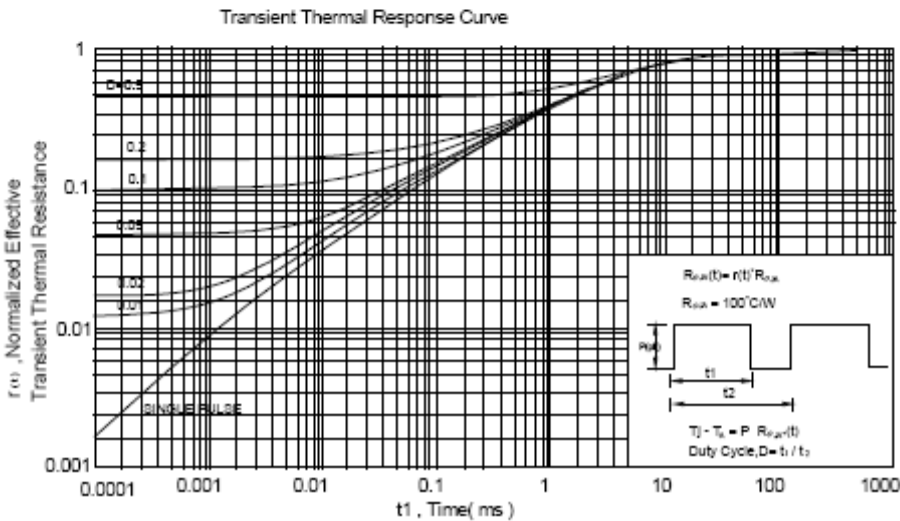
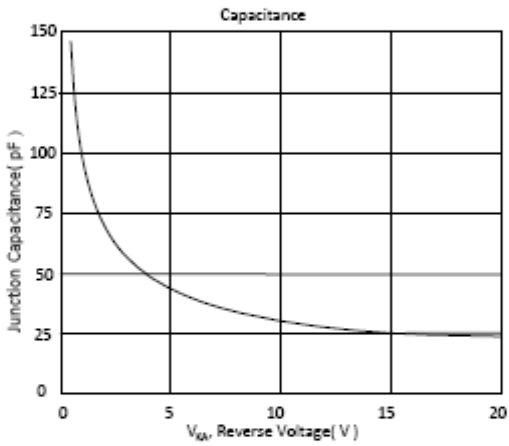
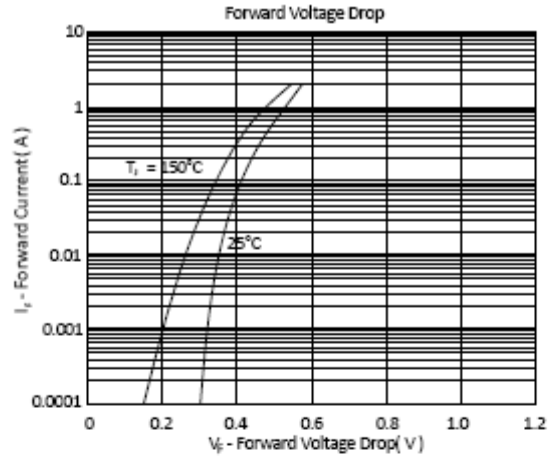
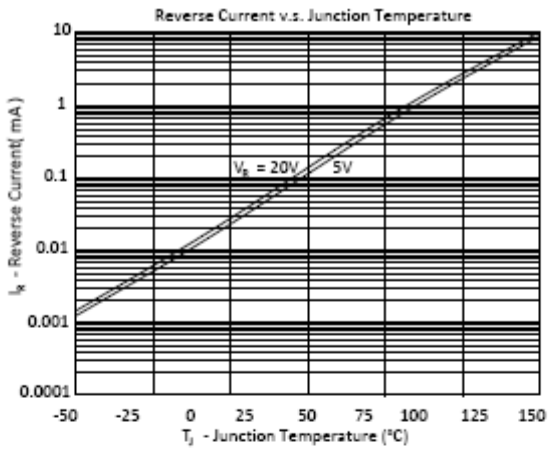




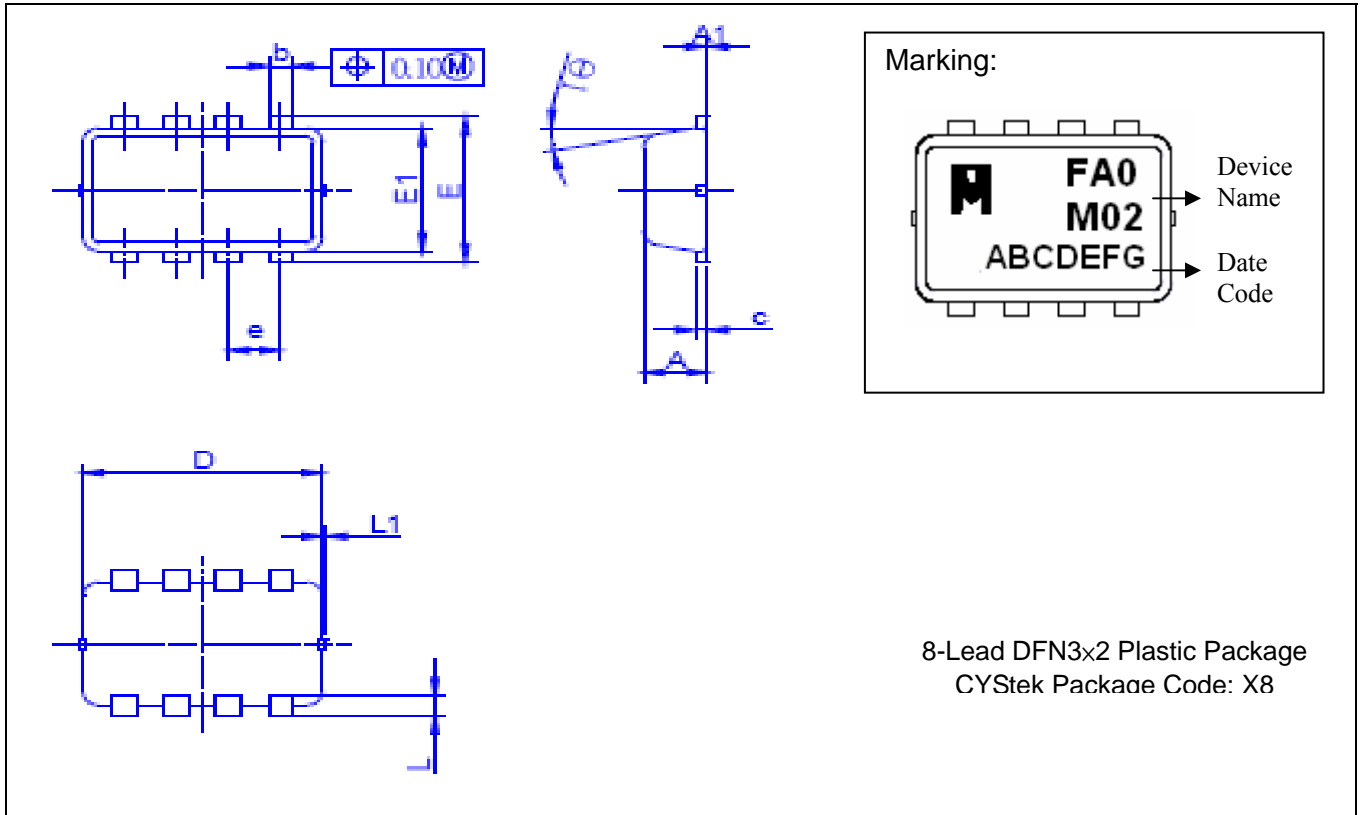
Characteristic Curves(Cont.)



Schottky Characteristic Curves



DFN3x2 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0276	0.0354	0.70	0.90	E1	*0.0689		*1.75	
A1	0.0000	0.0020	0.00	0.05	e	*0.0256		*0.65	
b	0.0094	0.0138	0.24	0.35	L	0.0079	0.0157	0.20	0.40
c	0.0031	0.0098	0.08	0.25	L1	0.0000	0.0039	0.00	0.10
D	*0.0118		*3.00		θ1	0°	12°	0°	12°
E	*0.0079		*2.00						

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: pure tin plated
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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